

Special Issue

Advances in Scalable Computing Services

Message from the Guest Editor

This Special Issue intends to gather the latest research and development results on the Dew Computing paradigm. It seeks original contributions, which demonstrate the theoretical and practical progress of Dew Computing, as well as implementation experiences from researchers in the area of Dew Computing, including but not limited to the following topics:

- Low-end distributed systems;
- Dew computing theory and vision;
- Dew computing structure and architecture;
- Dew, Cloudn and Fog computing integration and/or interrelation;
- Dew computing and IoT, ubiquitous computing;
- Dew computing and databases;
- Dew computing and blockchain;
- Dew computing and networks;
- Dew computing protocols and security;
- Dew computing applications.

Guest Editor

Prof. Dr. Karolj Skala

Center for Informatics and Computing Science, Ruđer Bošković Institute, 10000 Zagreb, Croatia

Deadline for manuscript submissions

closed (20 July 2022)



Applied Sciences

an Open Access Journal
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Impact Factor 2.5
CiteScore 5.5



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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls@mdpi.com

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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